

INTRODUCING LGA 3647 SOCKET & HARDWARE

- Meet future design needs with LGA 3647 sockets and hardware to meet Intel's next-generation CPU processors
- Provide higher performance, better system application scaling and better value



TE Connectivity's (TE) LGA 3647 socket and hardware meet the next-generation designs of Intel Corporation's (Intel) new CPU processors for higher performance and better system scaling. LGA 3647 socket is the first to feature a two-piece design that improves issues with warpage and offers better coplanarity and reliability. As one of a limited number of suppliers offering LGA 3647, TE has both socket and hardware parts available to bring you a full solution.

KEY BENEFITS

- Meet future design needs with LGA 3647 sockets and hardware that meet Intel's next-generation CPU processors
- Provide higher performance, better system application scaling and better value with new socket and hardware design
- Offer better coplanarity and reliability with a two-piece design that improves issues with warpage
- Help improve alignment and keep fingers away from the socket contact field with fabric and non-fabric carrier hardware
- Assist in orientation and alignment for the processor heatsink module (PHM) and the spring load force necessary for socket loading with the bolster plate hardware
- Supply mounting points for the bolster plate with back plate hardware

LEARN MORE

[LGA 3647 Socket Product Flyer](#)

[LGA Socket Landing Page](#)

[LGA 3647 Socket Part Listing](#)

[LGA 3647 Hardware Part Listing](#)

[LGA 3647 Parts List](#)

APPLICATIONS

- Servers
- Storage
- Data centers
- High-performance computing

ELECTRICAL

- Current rating: 0.5 Amps
- Insulation resistance: 500 megohms min. @ 500 VDC

MATERIALS

- Housing: LCP
- Contact: Copper alloy, 30µ" gold plated
- Cap: Thermoplastic

MECHANICAL

- Durability: 30 cycles

STANDARDS & SPECIFICATIONS

- Product specification #108-115115